

Title (en)
CHEMICAL COPPER PLATING SOLUTION

Publication
EP 0179212 B1 19911227 (EN)

Application
EP 85109921 A 19850807

Priority

- JP 20044584 A 19840927
- JP 27330384 A 19841226

Abstract (en)
[origin: EP0179212A2] There is disclosed a chemical copper plating solution containing a copper salt, a complexing agent, a reducing agent and a pH adjustor which further comprises at least one of the following Groups (A) and (B); Group (A); at least one non-ionic surface active agent selected from the group consisting of a non-ionic surface active agent having the formula: <CHEM> (wherein m1 and n1 each represent an integer of 1 or more) and a non-ionic surface active agent having formula: <CHEM> (wherein m2 and n2 each represent an integer of 1 or more), and at least one compound selected from the group consisting of 1,10-phenanthroline, a 1,10-phenanthroline derivative, 2,2'-bipyridyl, 2,2'-biquinoline and a water-soluble cyan compound; Group (B); an organic sulfur compound and an ethyleneamine compound.

IPC 1-7
C23C 18/40

IPC 8 full level
C23C 18/40 (2006.01)

CPC (source: EP)
C23C 18/40 (2013.01)

Citation (examination)

- FR 2436192 A1 19800411 - KOLLMORGEN TECH CORP [US]
- US 3902907 A 19750902 - KISHITA KAZUTAKA

Designated contracting state (EPC)
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